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OFFICE OF PETITIONS

Applicant: Ho et al.
Appl. No.: 10/605,305
Filing Date: September 22, 2003
U.S. Patent No.: 6,916,687
Issue Date: January 4, 2005
Title: BUMP PROCESS FOR FLIP CHIP PACKAGE
Attorney Docket No.: 10665-US-PA
Pub. No.: US 2004/0241911 A1
Pub. Date: December 2, 2004

This is in response to the request for correction of patent application publication under 37 CFR 1.221(b), which was received on April 27, 2005 for the above-identified application.

The instant request identifies errors in the published patent application publication. Since the application has already issued as U.S. Patent No. 6,916,687, the request is deemed moot.

The request is DISMISSED as moot.

Inquiries relating to this matter may be directed to Mark Polutta at (571) 272-7709 (voice).

Mark O. Polutta
Office of Patent Legal Administration
Office of the Deputy Commissioner
for Patent Examination Policy